

MODEL: HSS06-C20-P32 | DESCRIPTION: HEAT SINK

FEATURES

- TO-220 package
- solder pin
- copper alloy
- tin plated



MODEL

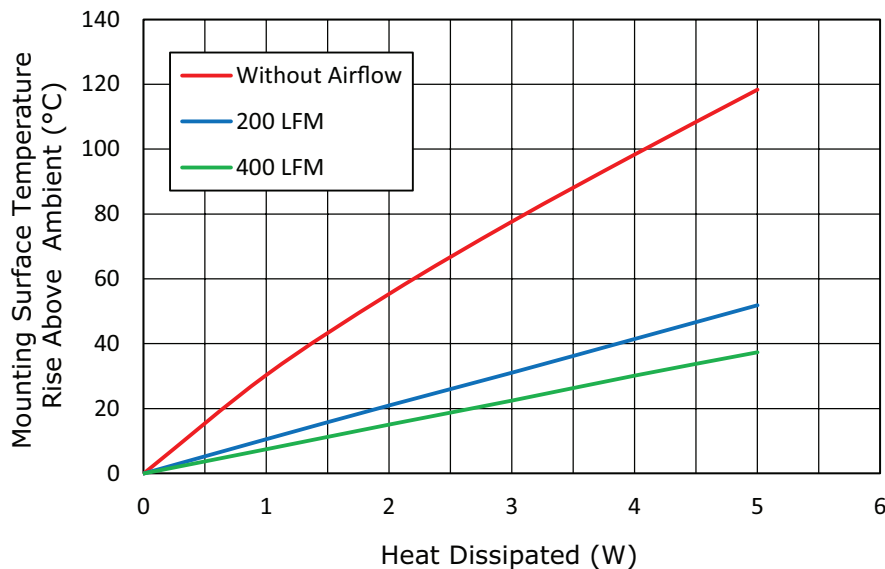
MODEL	thermal resistance ¹				power dissipation ¹ @ 75°C ΔT, nat conv (W)
	@ 75°C ΔT, nat conv (°C/W)	@ 1 W, nat conv (°C/W)	@ 1 W, 200 LFM (°C/W)	@ 1 W, 400 LFM (°C/W)	
HSS06-C20-P32	25.35	30.4	10.6	7.5	2.96

Note: 1. See performance curves for full thermal resistance details.

PERFORMANCE CURVES

Power (W)	Heatsink Temperature Rise Above Ambient (ΔT = T _{hs} - T _a) (°C)		
	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	30.4	10.6	7.5
2	55.4	21.0	15.1
3	77.7	31.1	22.5
4	98.4	41.5	30.2
5	118.4	51.9	37.4

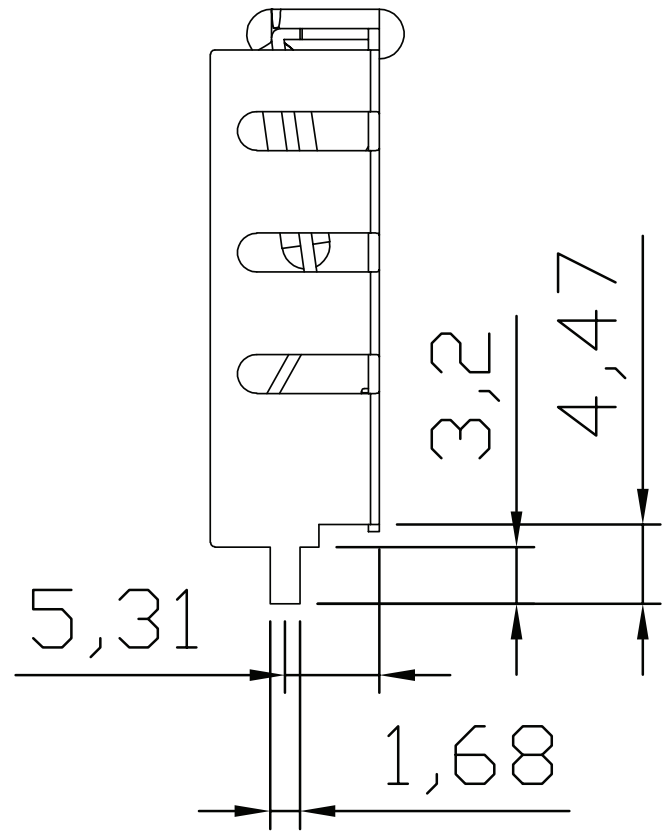
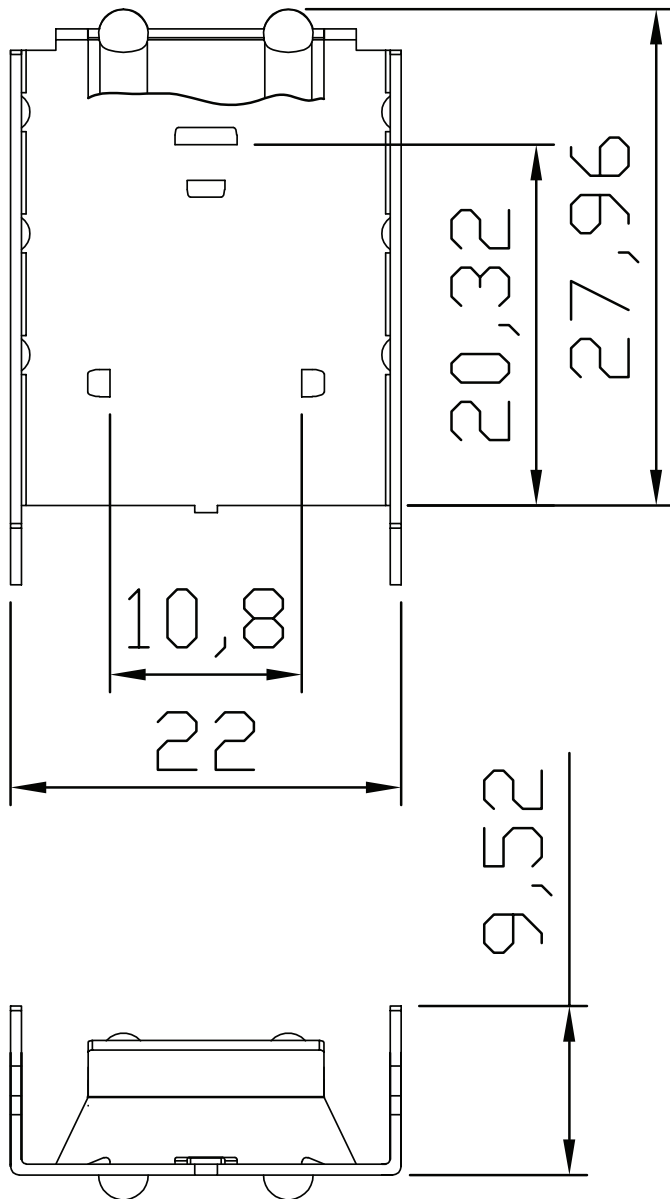
T_{hs}: "hot spot" temperature measured on the heatsink
T_a: ambient temperature



MECHANICAL DRAWING

units: mm
tolerance: ± 0.25 mm

MATERIAL	C1100
FINISH	tin
THICKNESS	0.6 mm
WEIGHT	7.7 g



REVISION HISTORY

rev.	description	date
1.0	initial release	06/25/2021

The revision history provided is for informational purposes only and is believed to be accurate.

CUI DEVICES

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